

Bill of Materials

TI DESIGNS

TIPD184: 100 A Closed Loop Current Sensor using Bi-Polar Supplies

Item #	Quantity	Value	Designator	Description	Manufacturer	Manufacturer Part Number	Supplier Part Number
1	1	N/A	N/A	Printed Wiring Board	Texas Instruments	N/A	
2	2	1.0 uF	C1 C4	1.0uF, 0603, Ceramic, X7R, 10V, 10%	Kemet	C0603C105K8RACTU	399-11133-1-ND
3	4	0.1 uF	C2 C3 C5 C6	0.1uF, 0603, Ceramic, X7R, 50V, 10%	Kemet	C0603C104K5RACTU	399-5089-1-ND
4	2	LED	D1 D2	Yellow LED	Lite-On	LTST-C191KSKT	160-1448-1-ND
5	1	Schottkey	D4	BAT54S, Dual Schottkey	Vishay	BAT54S-E3-08	BAT54S-E3-08CT-ND
6	1	NPN	Q1	NPN	Diodes Inc	BCX56TA	BCX56TACT-ND
7	1	PNP	Q2	PNP	Diodes Inc	BCX53TA	BCX53TACT-ND
8	2	200 ohm	R1 R4	200 ohm, 0603, 5%, .1W Resistor	Yageo America	RC0603JR-07200RL	311-200GRCT-ND
9	2	10K ohm	R5 R8	10K ohm, 0603, 1%, .1W Resistor	Yageo America	RC0603FR-0710KL	311-10KHRCT-ND
10	2	10K ohm	R13 R14	10K ohm, 0603, 0.1%, .1W Resistor	Yageo America	RT0603BRD0710KL	PHP49.9ACT-ND
11	1	49.9 ohm	R7	49.9 ohm, 1206, 0.1%, 1W Resistor	Vishay	PHP01206E49R9BST5	YAG1236CT-ND
12	1	470 ohm	R11	470 ohm, 0603, 5%, .1W Resistor	Yageo America	RC0603JR-07470RL	311-470GRCT-ND
13	2	40.2K ohm	R12 R15	40.2K ohm, 0603, 0.1%, .1W Resistor	Yageo America	RT0603BRD0740K2L	YAG1658CT-ND
15	1	Header	J1	4-pin, Single Row vertical mount male header	Samtec	TSW-104-14-T-S	
16	1	Sensor	U1	100 A Passive Current Sensor	Topstek	TQPL50A	
17	1	IC	U2	DRV411	Texas Instruments	DRV411AIRGPT	
18	1	IC	U3	TPS78950Q	Texas Instruments	TPS78950QDGNRQ1	
19	1	IC	U4	OPA237	Texas Instruments	OPA237UA	

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